



Abstract: (Fig. 3)

"RESIN SEALING TYPE SEMICONDUCTOR DEVICE IN WHICH A
VERY SMALL SEMICONDUCTOR CHIP IS SEALED IN PACKAGE
WITH RESIN"

5 A lead of a lead frame cannot be made close to a
very small semiconductor chip in view of processing
dimensions. If a TAB technique is used to directly con-
nect the semiconductor chip and the lead in order to
10 improve in reliability, a device for forming a bump on
an electrode of the chip is required, which increases
the cost of investment in equipment. A printed circuit
board (33) is formed between the lead (34) and bed (31)
and a bonding wire (37) is used to shorten the length of
15 wiring and thus to decrease in cost and improve in
reliability. Since an electrode pad (35) of the semi-
conductor chip (32), the printed circuit board (33), and
the lead (34) are connected to each other using the TAB
technique, the productivity of semiconductor devices is
increased. Using the TAB technique, no bumps are formed
anywhere and the cost of investment in equipment is not
so increased.